Converter itself: 2.5mm by 1.5mm

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

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<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
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COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

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| PLOT NAME = Bottom Assembly Drawing | GENERATED: 9/4/2014 3:37:40 PM | TEXAS INSTRUMENTS |
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